AMENDMENTS TO THE SPECIFICATION

Please replace paragraphs [0009] and [0032] as follows:

[0009] From the related art documents mentioned above it is apparent that there was a technical prejudice in the field according to which a foamed layer were to be considered unsuitable for being used as the semiconductive insulation shield of a cable since the presence of voids within the semiconductive foamed layer was believed to be dangerous from the electrical point of view. In fact all said documents disclose an electrical cable comprising a compact, i.e. non-foamed, insulation shield which can be associated with a foamed layer for ~~provided~~ providing the cable with waterblocking and/or impact resistance properties.

[0032] The Applicant has found that the distance/time that the insulation shield material is maintained above the decomposition temperature in the CV tube is an important parameter for obtaining the desired density reduction (and possibly surface quality) in the insulation shield due to foaming. In one instance the Applicant has found that when the insulation shield attains a temperature in the CV tube just above the foaming agent's decomposition temperature, the density reduction of the insulation shield due to foaming was increased from a 5% reduction to a 26% reduction by increasing the time the shield was kept above the decomposition temperature by about 1.5 times, from 5.8 minutes to 8.6 minutes. Keeping all other parameters constant, it the Applicant has found that reducing the decomposition temperature of the foaming agent, decreasing the line speed to increase this time, or alternating the temperature profile of the CV tube to increase this time, will each aid in obtaining the desired density reduction. Further, while, for example, the decomposition temperature may be around

200° C. [~390° F.] (or significantly less such as about 160° C. [~320° F.] depending on the foaming agent used) many of the foaming agents suitable for the present invention have a recommended processing temperature range of 210° C. to 240° C. [~410° F. to 464° F.] (or more, again depending on the foaming agent used) to achieve optimum gas yield. Thus, it was found that even if linespeed were increased, thereby decreasing the time the insulation shield was above the decomposition temperature to about 3 minutes, satisfactory results could still be obtained by altering the tube temperature profile such that the insulation shield was in the recommended processing temperature range of the foaming agent for more than one minute.